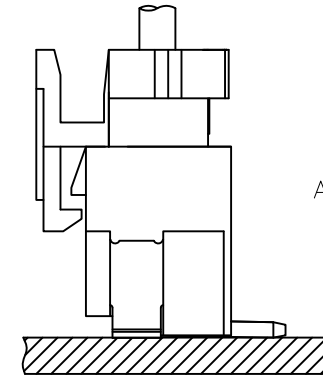
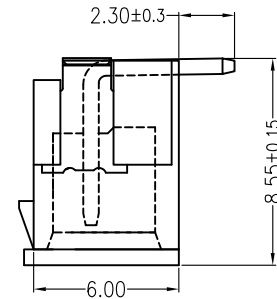
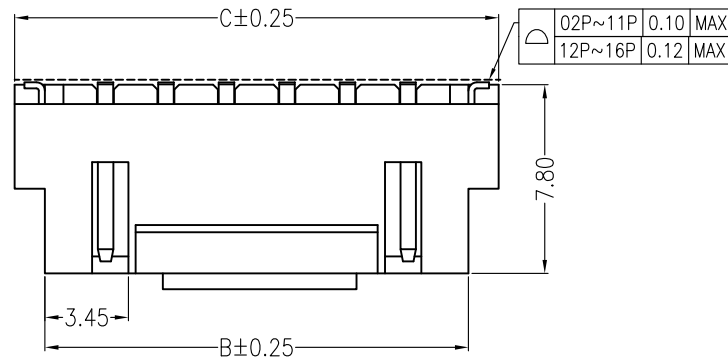
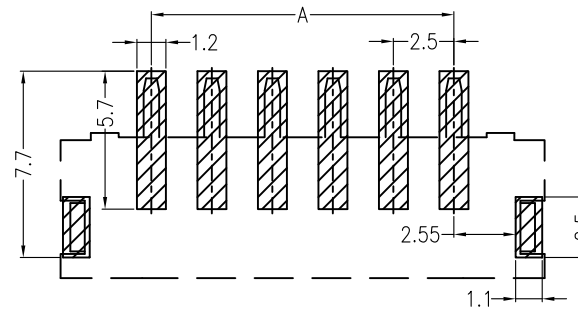
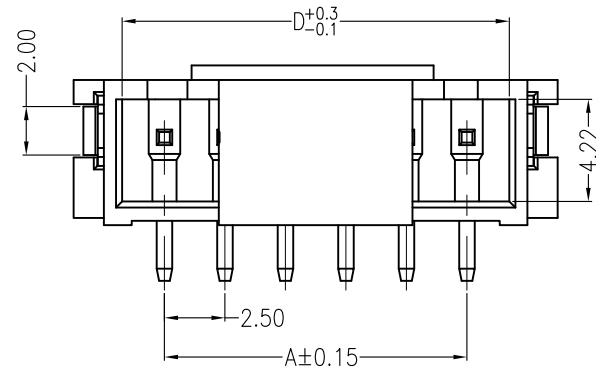


修订 REV	标记 MARK	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE
AO		NEW RELEASE	黄艳兰	2018-04-19



Assembly Layout

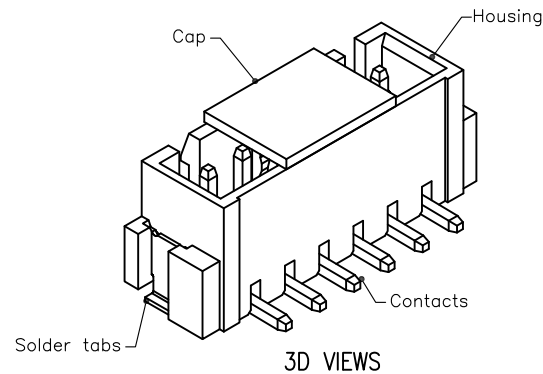


SUGGESTED PCB LAYOUT

Circuit	Dimensions (mm)			
	DIM. A	DIM. B	DIM. C	DIM. D
02	2.50	7.50	10.00	6.00
03	5.00	10.00	12.50	8.50
04	7.50	12.50	15.00	11.00
05	10.00	15.00	17.50	13.50
06	12.50	17.50	20.00	16.00
07	15.00	20.00	22.50	18.50
08	17.50	22.50	25.00	21.00
09	20.00	25.00	27.50	23.50
10	22.50	27.50	30.00	26.00
11	25.00	30.00	32.50	28.50
12	27.50	32.50	35.00	31.00
13	30.00	35.00	37.50	33.50
14	32.50	37.50	40.00	36.00
15	35.00	40.00	42.50	38.50
16	37.50	42.50	45.00	41.00

Specifications:

- Contact resistance: $\leq 20m\Omega$
- Insulation resistance: $\geq 1000M\Omega$
- Rated voltage: 250V AC DC
- Rated current: 3.0A AC DC
- Withstand voltage: 1000V AC/minute
- Temperature range: $-25^{\circ}C \sim +105^{\circ}C$
- Housing: LCP, UL94V-0, Natural
- Cap: LCP, UL94V-0, Natural
- Contacts: Brass/Sn
- Solder tabs: Phosphor Bronze/Sn



3D VIEWS

HDGC 深圳市华德共创科技有限公司
 Shenzhen Huade co-create Technology Co., LTD
 TEL : 0755-27129737 FAX : 0755-29940187

-TOLERANCES- UNLESS OTHERWISE SPECIFIED 公差参数表				TITLE: 产品名称: XH2.5带扣立贴	
X.X	±0.30	X.X°	±3°	APPD: 核准: 谢亮	PART NO: 产品编号: HDGC2512WV-S-XP
X.XX	±0.30	X.XX°	±2°	CHECK: 校对: 王建业	DATE
X.XXX	±0.10	X.XXX°	±1°	DRAW: 绘图: 黄艳兰	SCALE
					UNIT
					CODE NUMBER
					1 : 1
					mm
					A018